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Notice of Allowability	Application No.	Applicant(s)
	10/633,434	KIM ET AL.
	Examiner	Art Unit
	Hsien-ming Lee	2823
The MAILING DATE of this communication appeal All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT Report of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this or other appropriate communicat GHTS. This application is subject.	application. If not included tion will be mailed in due course. THIS
1. This communication is responsive to <u>11/8/04 and 12/6/04</u> .		
2. The allowed claim(s) is/are 1-36 and 64-75.		
3. The drawings filed on <u>01 August 2003</u> are accepted by the	Examiner.	
 4. Acknowledgment is made of a claim for foreign priority unally all b) Some* c) None of the: Certified copies of the priority documents have Certified copies of the priority documents have Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: 	e been received. e been received in Application No.	
Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONN THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.	•	ply complying with the requirements
5. A SUBSTITUTE OATH OR DECLARATION must be subm INFORMAL PATENT APPLICATION (PTO-152) which give		
 6. CORRECTED DRAWINGS (as "replacement sheets") must (a) including changes required by the Notice of Draftspers 1) hereto or 2) to Paper No./Mail Date	son's Patent Drawing Review (PT s Amendment / Comment or in the .84(c)) should be written on the dra he header according to 37 CFR 1.13 sit of BIOLOGICAL MATERIA	e Office action of wings in the front (not the back) of 21(d). L must be submitted. Note the
Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☐ Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material	6. Interview Summa Paper No./Mail I 98), 7. Examiner's Amer	Date
		Primary Examiner Art Unit: 2823

DETAILED ACTION

Remarks

1. Applicant's RCE filing on 12/6/2004 is acknowledged. Claims 1-36 and 64-75 are pending in the application.

Allowable Subject Matter

- 2. Claims 1-36 and 64-75 are allowed.
- The following is an examiner's statement of reasons for allowance:

 The prior art of record, Cobbley et al. (US 2002/0068379), teaches a related art, comprising:
 - a lead frame 112 comprising a plurality of lead fingers 128, a plurality of interconnect bonding sites (i.e. the opposite portion with respect to terminal bonding sites 138) on the lead fingers 128 (Fig.5), a plurality of terminal bonding sites 138 in an area array and at least one bus bar 132 in the area array;
 - a semiconductor die 110 comprising a circuit side (i.e. front face 114 of the die 110),
 a plurality of die contacts 116 (i.e. bond pads) on the circuit side; and
 - a plurality of interconnects 130 (i.e. bond wires) bonded to the die contacts 116.

In contrast, Cobbley et al. at least neither teach nor suggest that a plurality of terminal bonding sites on the top portions on the second surface (claim 1), wherein the second surface is opposing to a first surface; a plurality of terminal contacts attached to terminal bonding sites (claim 1); a semiconductor die having a back side attached to leadfingers on a first side and substantially covering a bus bar and an encapsulant encapsulating a die, interconnects and a leadframe (claim 5); a semiconductor die comprising a circuit side, a plurality of die contacts on

the circuit side and a back side attached to a leadframe and a plurality of terminal contacts on terminal bonding sites (claim 14); a plurality of terminal bonding sites on the leadfingers on the opposing second side in an area array (claim 20); a semiconductor die having a back side attached to die mounting side and a leadframe comprising a plurality of leadfingers having tip portions configured to form the die mounting sit on a first side (claim 27); and a plurality of terminal bonding sites on an opposing second surface of leadfingers in an area array and a semiconductor die back bonded to the leadfingers substantially covering a bus bar (claims 64 and 70).

Therefore, the instant invention is neither anticipated nor rendered obvious over the prior art of record.

- 4. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."
- 5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hsien-ming Lee whose telephone number is 571-272-1863. The examiner can normally be reached on Tuesday-Thursday ($8:00 \sim 6:00$).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on 571-272-1855. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Hsien-ming Lee Primary Examiner Art Unit 2823

Feb 3, 2005

HSIEN-MING LEE PRIMARY EXAMINED 2/3/2015